

CLAIMS

1. A flip-chip packaging method, wherein
in flip-chip packaging a semiconductor element on a
5 circuit board by using conductive resin, said element having
protruding electrodes formed thereon, the method comprising:

printing an electrode material containing
photopolymerizable materials on a semiconductor element
package region on said circuit board such that a film is formed
10 with a prescribed thickness, and forming concave circuit
electrodes by baking said electrode material film after
performing exposure and development of said electrode
material film to allow said electrode material film to remain
only on prescribed electrode regions, thereby forming concave
15 circuit electrodes having edges warped in a direction of going
apart from the circuit board surface; and

bringing said protruding electrodes formed on said
semiconductor element into abutment with concave faces of
said concave circuit electrodes, and connecting said
20 protruding electrodes and said circuit electrodes with each
other via the conductive resin.

2. The flip-chip packaging method according to claim 1,
wherein said electrode material film is formed to have a dry
25 film thickness of 10 to 20 micrometers.

3. The flip-chip packaging method according to claim 1 or
2, wherein said electrode material film remaining after
development is trapezoidal in cross section that is wider as
30 it goes farther away from said circuit board.

4. The flip-chip packaging method according to claim 1 or
2, wherein said circuit electrode is arc-shaped in cross
section.

5. A flip-chip package in which a semiconductor element having protruding electrodes formed thereon is packaged on a circuit board by using conductive resin, wherein

5 said circuit board includes concave circuit electrodes each having edges warped in a direction of going apart from the circuit board surface,

said semiconductor element is disposed such that ends of said protruding electrodes thereof come in abutment with concave surfaces of said concave circuit electrodes, and

10 said protruding electrodes and said circuit electrodes are connected to each other via the conductive resin.

6. A circuit board for flip-chip packaging a semiconductor element by using conductive resin, said element having
15 protruding electrodes formed thereon, comprising concave circuit electrodes each having edges warped in a direction of going apart from the circuit board surface.